IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND these claims and ADD new claims in accordance with the following:

1. (CURRENTLY AMENDED) An optical communication device, comprising:

a printed circuit board;

an optical element ~~co-axial laser diode~~ module arranged near a first side of ~~connected to~~ the printed circuit board and having a first surface perpendicular to the printed circuit board;

a plurality of driving ~~main~~ signal leads provided on the first surface of the optical element module ~~co-axial laser diode module~~ for supplying driving signals to the optical element module;

~~an~~ monitoring ~~auxiliary~~ signal lead provided on the first surface of the optical element module~~co-axial laser diode module~~ for supplying a monitoring signal to the optical element module;

a plurality of driving signal lands provided on the printed circuit board and connected to the driving ~~main~~ signal leads and a monitoring signal land connected to the monitoring ~~auxiliary~~ signal lead;

wherein the ~~lands~~driving signal lands connected to the driving ~~main~~ signal leads are arranged near ~~in proximity to~~ the first side ~~an end~~ of the printed circuit board so as to reduce lengths of the driving signal leads; and

the monitoring signal land connected to the monitoring ~~auxiliary~~ signal lead is situated farther away from the first side ~~end~~ of the printed circuit board than the lands connected to the driving ~~main~~ signal leads so as to increase the physical separation between the driving signal lands.

2. (CURRENTLY AMENDED) The optical communication device as claimed in

claim 1, wherein the monitoring signal land connected to the monitoring~~auxiliary~~ signal lead~~of the co-axial laser diode module~~ is enclosed in an insulating material.

3. (CURRENTLY AMENDED) The optical communication device as claimed in claim 2, wherein the driving signal lands connected to the ~~main~~driving signal leads~~of the co-axial laser diode module~~ are enclosed in the insulating material except for the~~ir~~ sides of the lands near the first side ~~at the end~~ of the printed circuit board.

4. (CURRENTLY AMENDED) The optical communication device as claimed in claim 1, wherein the ~~co-axial laser diode~~ optical element module is arranged so that~~positions of~~ the ~~main~~driving signal leads ~~on the co-axial laser diode module~~are nearer ~~closer~~ to the printed circuit board than~~a position of said auxiliary~~ the monitoring signal lead ~~on the co-axial laser diode module~~.

5. (CURRENTLY AMENDED) The optical communication device as claimed in claim 4, wherein the ~~co-axial laser diode~~ optical element module is arranged so that~~the positions of~~ the ~~main~~driving signal leads~~on the co-axial laser diode module~~ are ~~in proximity of~~ near the first side of the printed circuit board.

6. (CURRENTLY AMENDED) The optical communication device as claimed in claim 1, wherein one of the ~~said plurality of main~~driving signal leads~~of the co-axial laser diode module~~ are ~~is~~set at a common potential, and is commonly used by the ~~main~~driving signals and the ~~auxiliary~~monitoring signal.

7. (NEW) A method comprising:

providing a printed circuit board;

arranging an optical element module near a first side of the printed circuit board and having a first surface perpendicular to the printed circuit board;

arranging a plurality of driving signal leads on the first surface of the optical element module for supplying driving signals to the optical element module;

arranging a monitoring signal lead on the first surface of the optical element module for supplying a monitoring signal to the optical element module;

providing a plurality of driving signal lands on the printed circuit board to connect to the plurality of driving signal leads;

providing a monitoring signal land on the printed circuit board to connect to the monitoring signal lead; and

positioning the monitoring signal land connected to the monitoring signal lead farther away from the first side of the printed circuit board than the plurality of driving signal lands connected to the plurality of driving signal leads so as to increase the physical separation between the plurality of driving signal lands thereby suppressing degradation of pulse shapes and high-frequency characteristics of the driving signals in the optical communications device.

8. (NEW) The method according to claim 7, further comprising:

enclosing the monitoring signal land connected to the monitoring signal lead in an insulating material.

9. (NEW) The method according to claim 8, further comprising:

enclosing the driving signal lands connected to the driving signal leads in an insulating material except for sides of the driving signal lands on the first side of the printed circuit board.

10. (NEW) The method according to claim 7, further comprising:

arranging the optical element module so that the plurality of driving signal leads are nearer to the first side of the printed circuit board than the monitoring signal lead.

11. (NEW) The method according to claim 10, further comprising:

arranging the optical element module so that the plurality of driving signal leads are near the first side of the printed circuit board.

12. (NEW) The method according to claim 7, further comprising:

setting one of the driving signal leads at a common potential, such that it is commonly used by the driving signals and the monitoring signal.

13. (NEW) An Apparatus comprising:

a printed circuit board;

an optical element module near a first side of the printed circuit board and having a first surface perpendicular to the printed circuit board;

a plurality of driving signal leads on the first surface of the optical element module for supplying driving signals to the optical element module;

monitoring signal leads on the first surface of the optical element module for supplying one or more monitoring signals to the optical element module;

a plurality of driving signal lands on the printed circuit board to connect to the plurality of driving signal leads; and

a monitoring signal land connected to the monitoring signal lead;

wherein, the monitoring signal land connected to the monitoring signal lead is positioned farther away from the first side of the printed circuit board than the plurality of driving signal lands connected to the plurality of driving signal leads so as to increase the physical separation between the plurality of driving signal lands.

14. (NEW) The apparatus according to claim 13, further comprising:

enclosing the monitoring signal land connected to the monitoring signal lead in an insulating material.

15. (NEW) The apparatus according to claim 14, further comprising:

enclosing the driving signal lands connected to the driving signal leads in an insulating material except for sides of the driving signal lands on the first side of the printed circuit board.

16. (NEW) The apparatus according to claim 13, further comprising:

arranging the optical element module so that the driving signal leads are nearer to the first side of the printed circuit board than the monitoring signal lead.

17. (NEW) The apparatus according to claim 16, further comprising:

arranging the optical element module so that the driving signal leads are near the first side of the printed circuit board.

18. (NEW) The apparatus according to claim 13, further comprising:

setting one of the driving signal leads at a common potential, such that it is commonly used by the driving signals and the monitoring signal.

19. (NEW) The apparatus according to claim 16, further comprising:

enabling the suppression of degradation of pulse shapes and high-frequency characteristics of the driving signals by shortening the lengths of the driving signal leads.